

T-1(3mm) ROUND LED LAMP

Part Number: WP937IID

High Efficiency Red

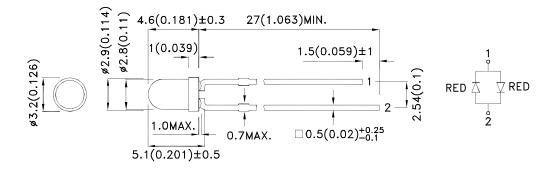
Features

- Uniform light output.
- Low power consumption.
- Long life solid state reliability.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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REV NO: V.5A CHECKED: Allen Liu **DATE: MAR/29/2013**

DRAWN: F.Cui

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
WP937IID	LI' L E'' :		4	10	- 60°
	High Efficiency Red (GaAsP/GaP)	Dad Different	*2	*4	
	High Efficiency Red (GaAsP/GaP)	Red Diffused	4	10	
			*2	*4	

Notes:

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	IF=20mA

Notes:

- 1.Wavelength: +/-1nm.
 2. Forward Voltage: +/-0.1V.
 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

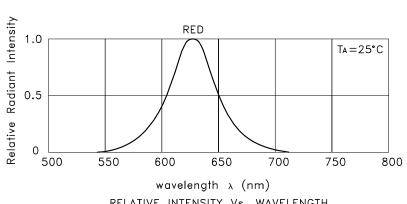
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red			
Power dissipation	75			
DC Forward Current	30			
Peak Forward Current [1]	160			
Electrostatic Discharge Threshold (HBM)	8000	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2] 260°C For 3 Seconds				
Lead Solder Temperature [3] 260°C For 5 Seconds				

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 3. 5mm below package base.

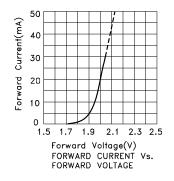
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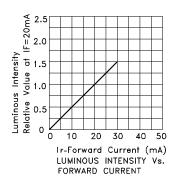
Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

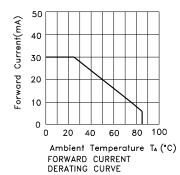


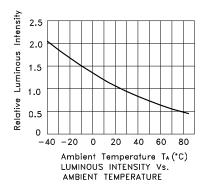
RELATIVE INTENSITY Vs. WAVELENGTH

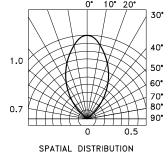
High Efficiency Red WP937IID



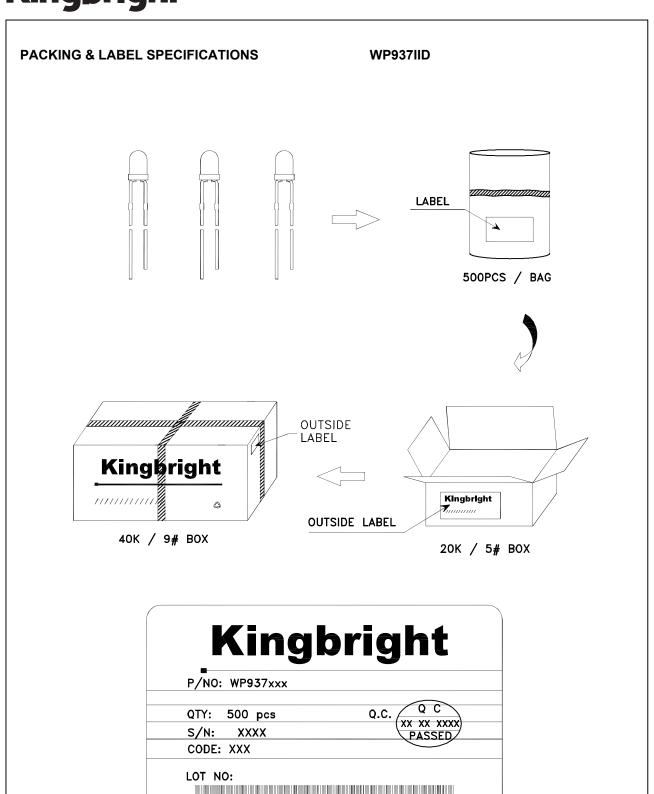








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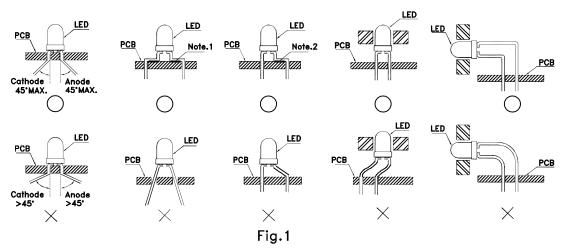
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RoHS Compliant

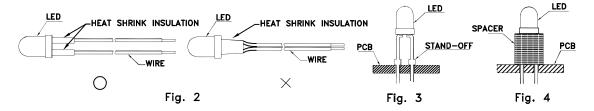
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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



- " \bigcirc " Correct mounting method "imes" Incorrect mounting method
- 2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig.2)
- 3. Use stand—offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

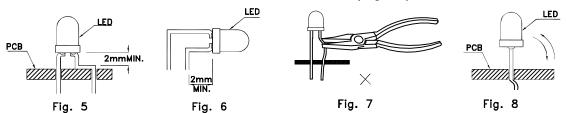


- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

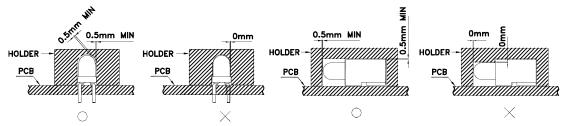
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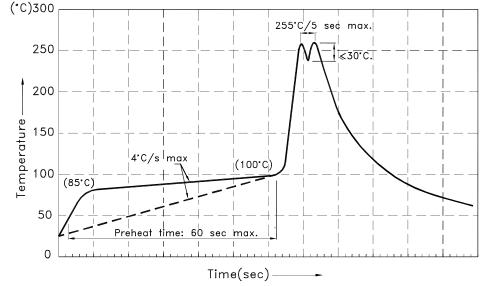
6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 8. The tip of the soldering iron should never touch the lens epoxy.
- 9. Through—hole LEDs are incompatible with reflow soldering.
- 10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 11. Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process. 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

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